

Specially designed for High-density SMT



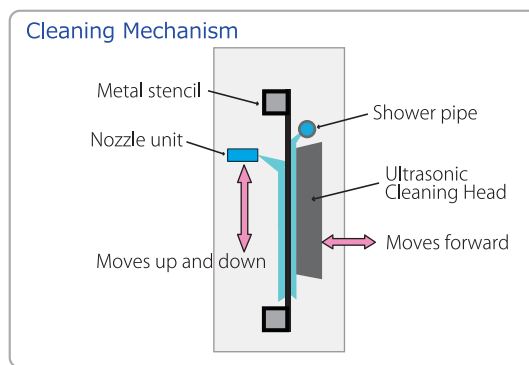
SC-BM500-E



The picture shows SC-BM500-E

Precise Cleaning

Ultrasonic combined to spray cleaning provides excellent solution for all kinds of applications including wafer bump and electroform stencils.



Wide range stencils applicable

Stencil size
320×320mm*



Stencil size
1000×740mm



* Adapter required.

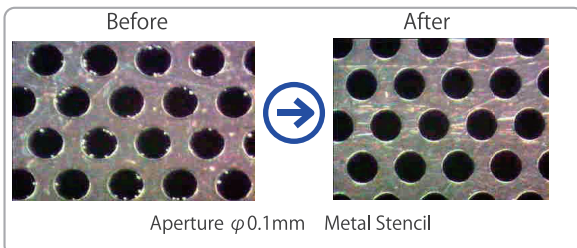
Stencils from 320mm × 320mm to 1000 × 740mm can be set easily. Recommended to customers using multiple types of stencils.

M : Mesh screen
S : Semiconductor

Two packages available to meet customer needs

All models are equipped with a convenient touch panel screen.

Cleaning Ability



Product No.	SC-BM500-E
Outside dimension	SC-BM500-E : W 780 D 1,260 H 2,250mm (including projecting parts)
Weight	250kg
Power	AC 110, 120, 220, 240V 50/60Hz
Power consumption(VA)	550VA
Ultrasonic	40 k Hz 300W
Air	0.4MPa 600NL/min
Exhaust duct	5m/sec
Cleaning time	Approx. 3min.*
Drying time	Approx. 17min.*

※ When using our recommended solvent HA-1285U.

